

FIG.1

FIG.2

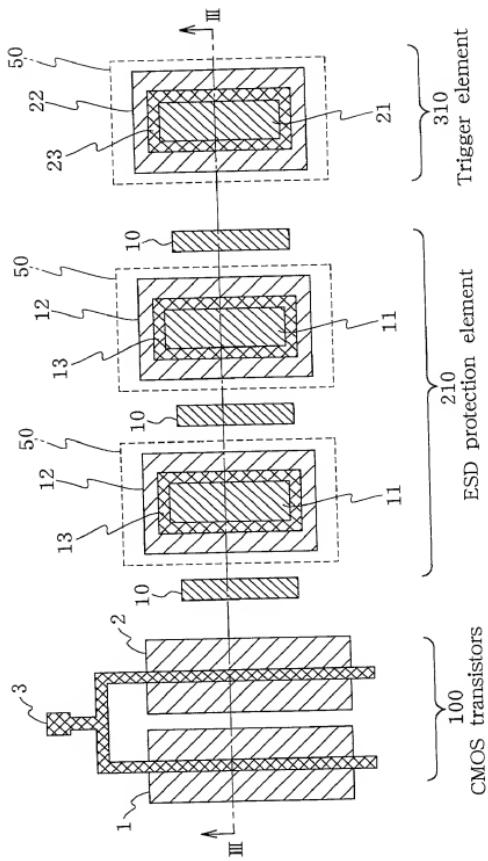


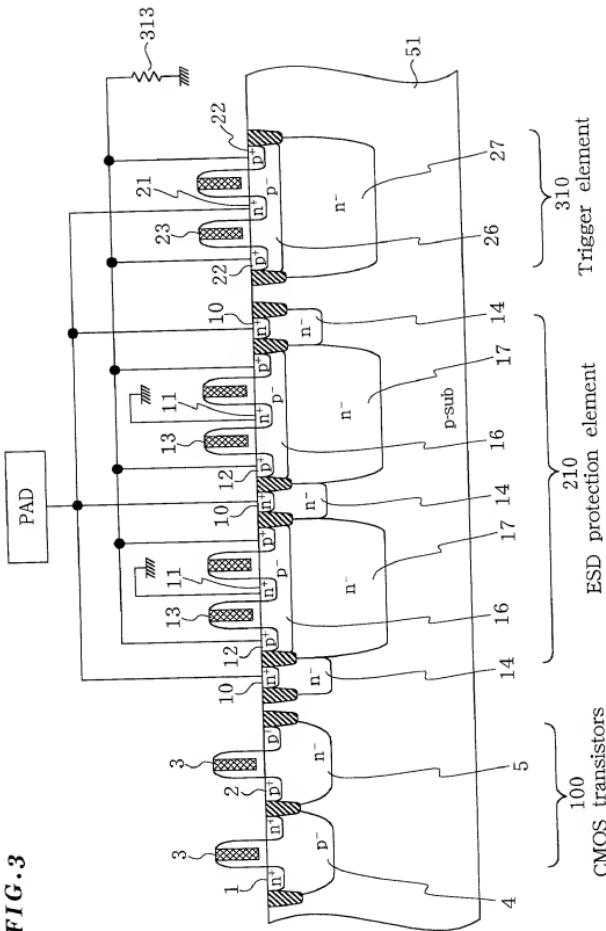
FIG. 3

FIG.4

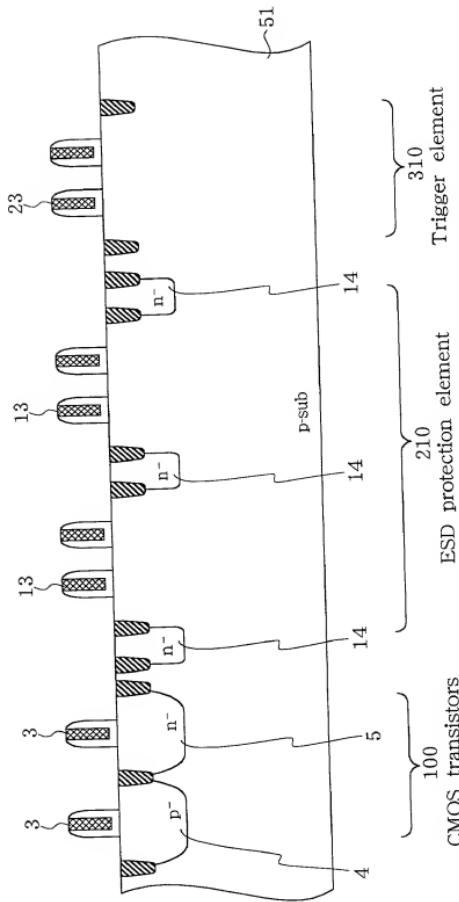


FIG. 5

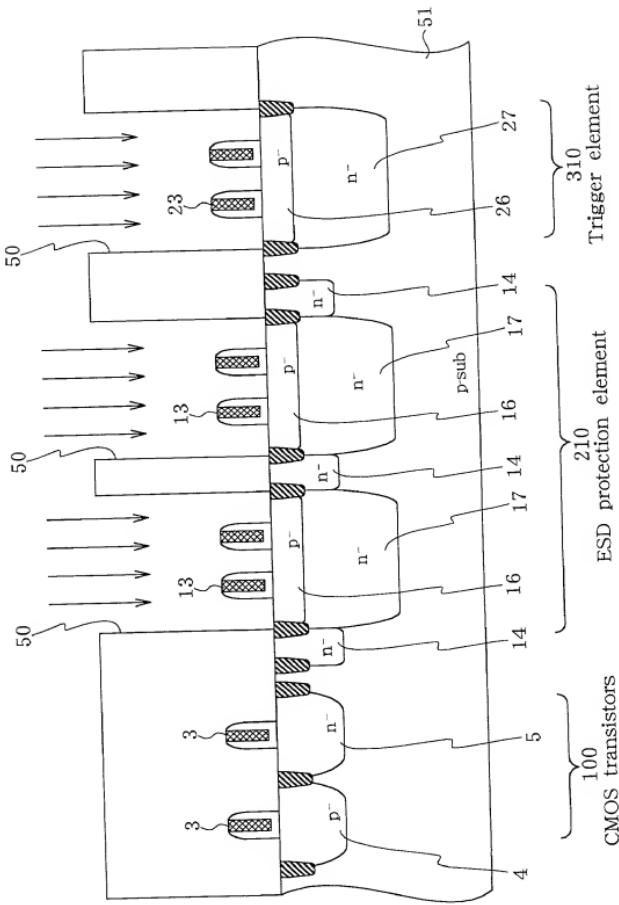
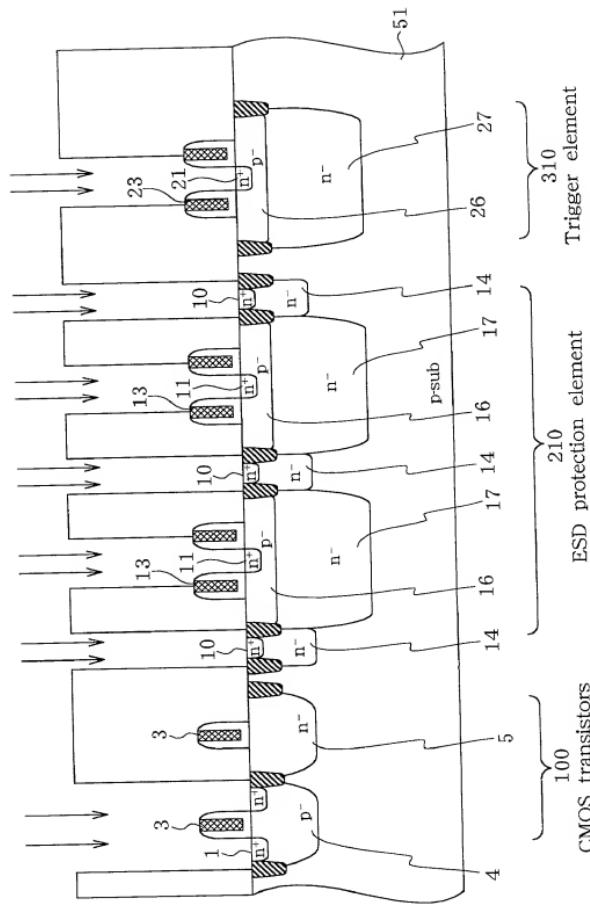


FIG. 6



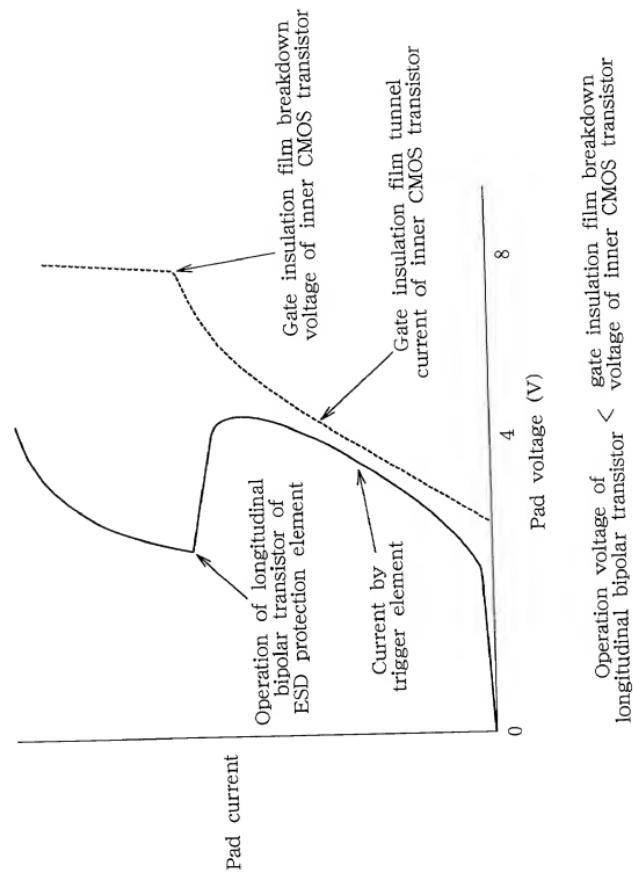


FIG.7

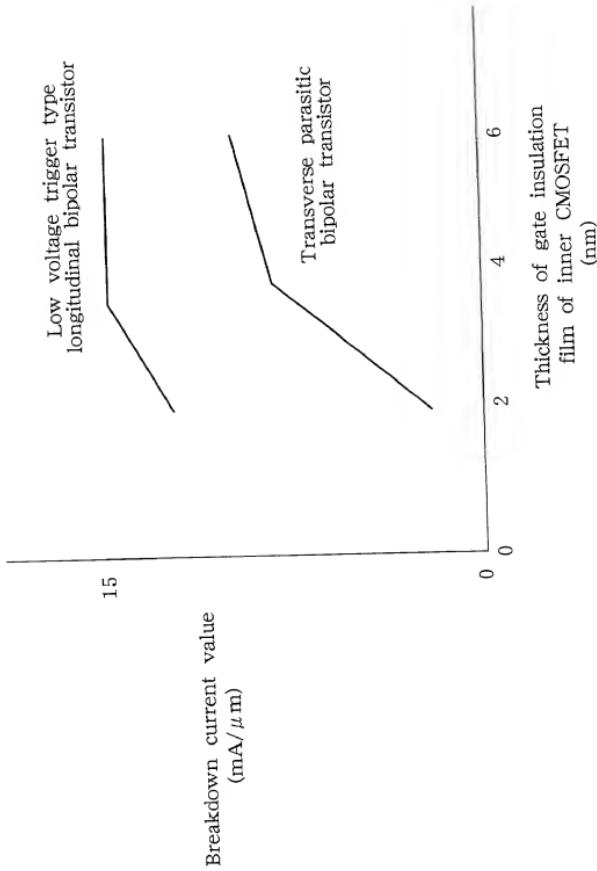
FIG. 8

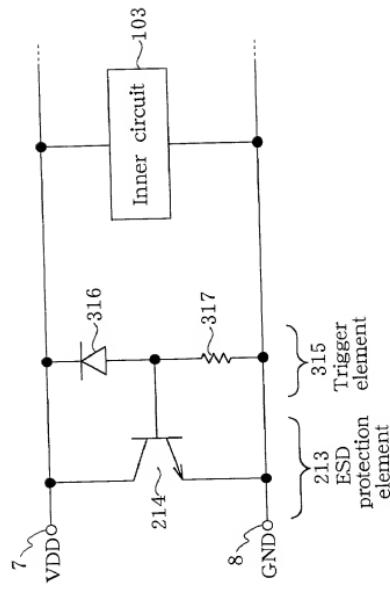
FIG.9

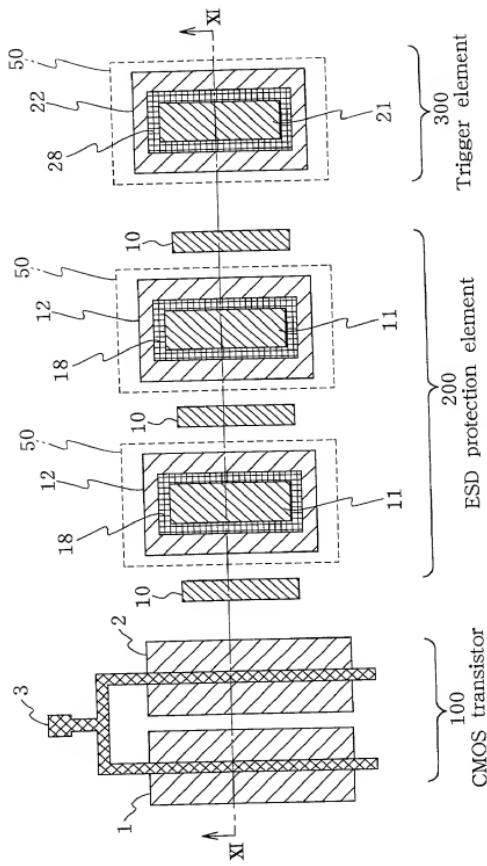
FIG.10

FIG. 11

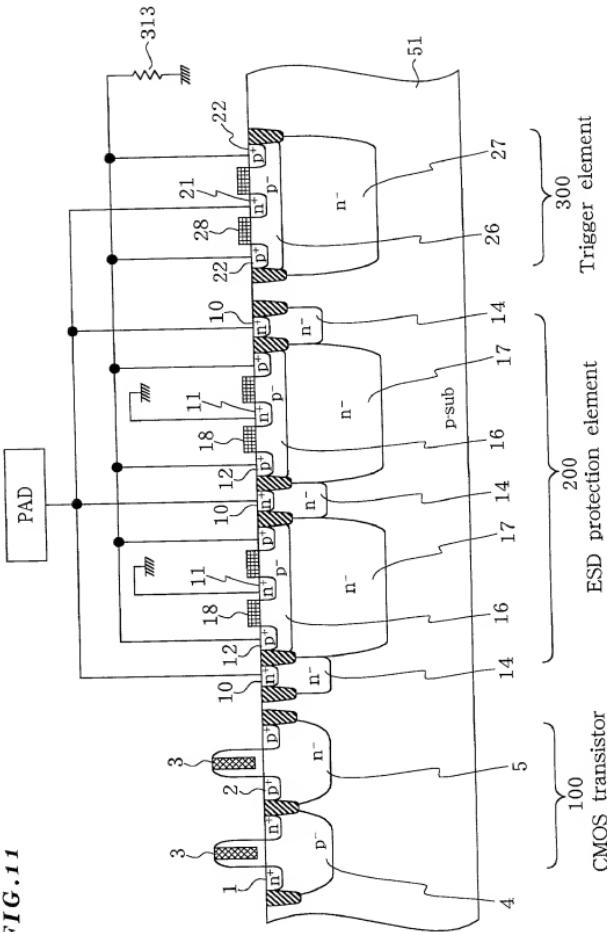


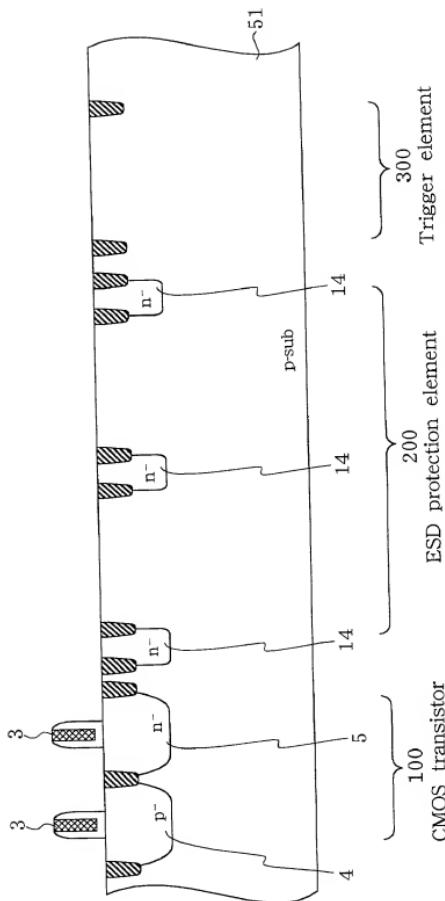
FIG. 12

FIG. 1.13

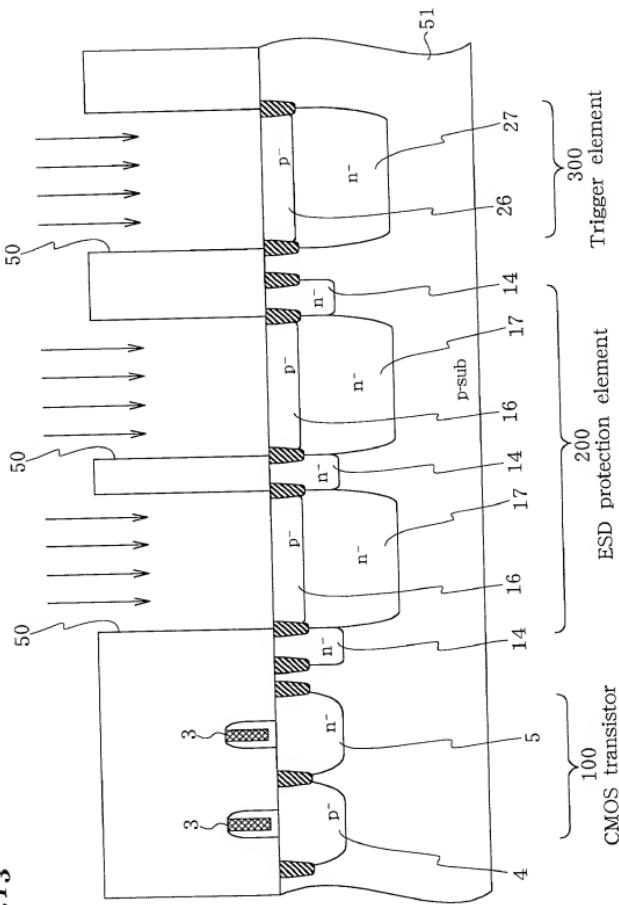


FIG. 14

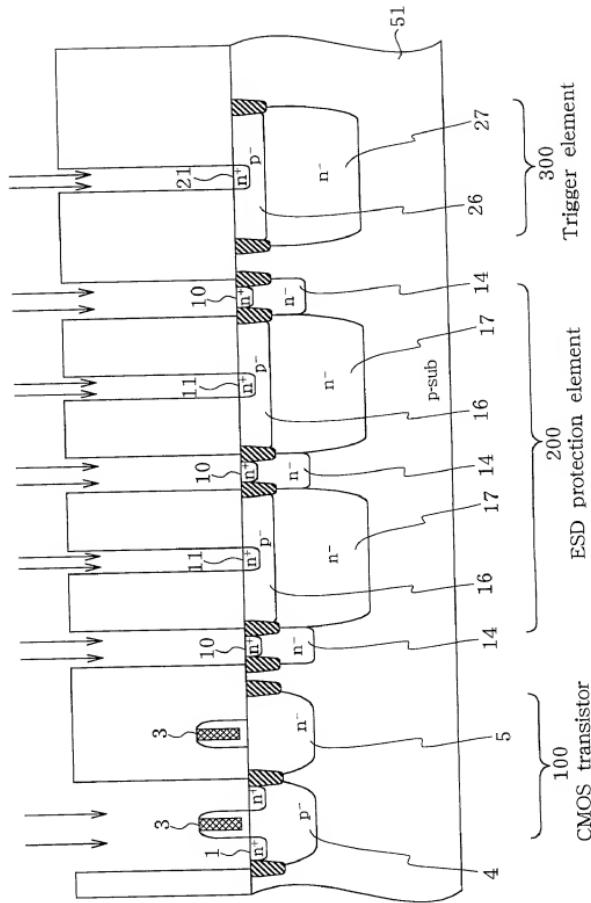
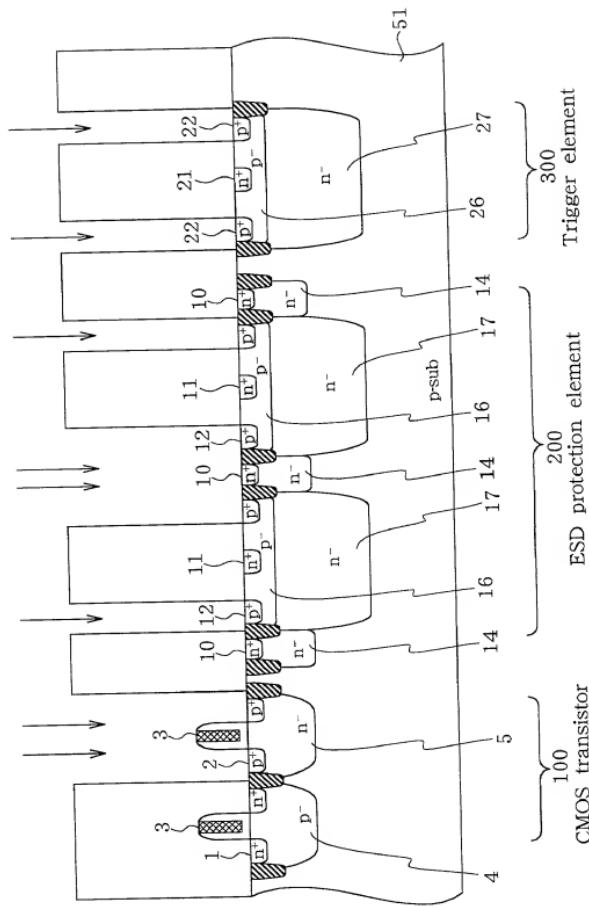


FIG. 1.5



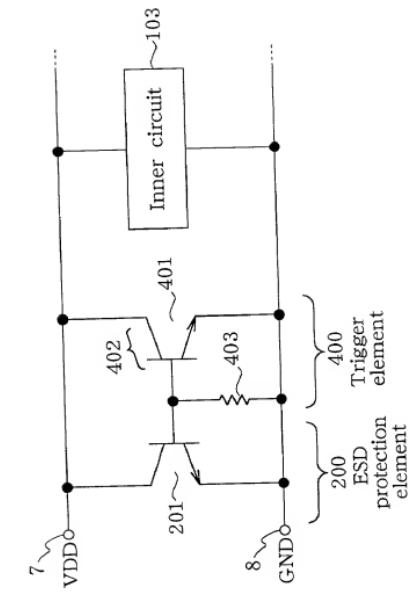


FIG.16

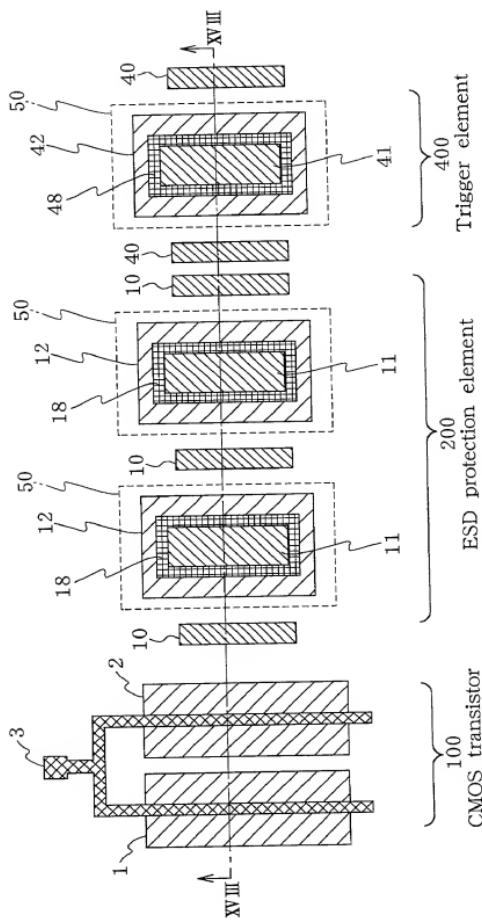
FIG.17

FIG. 18

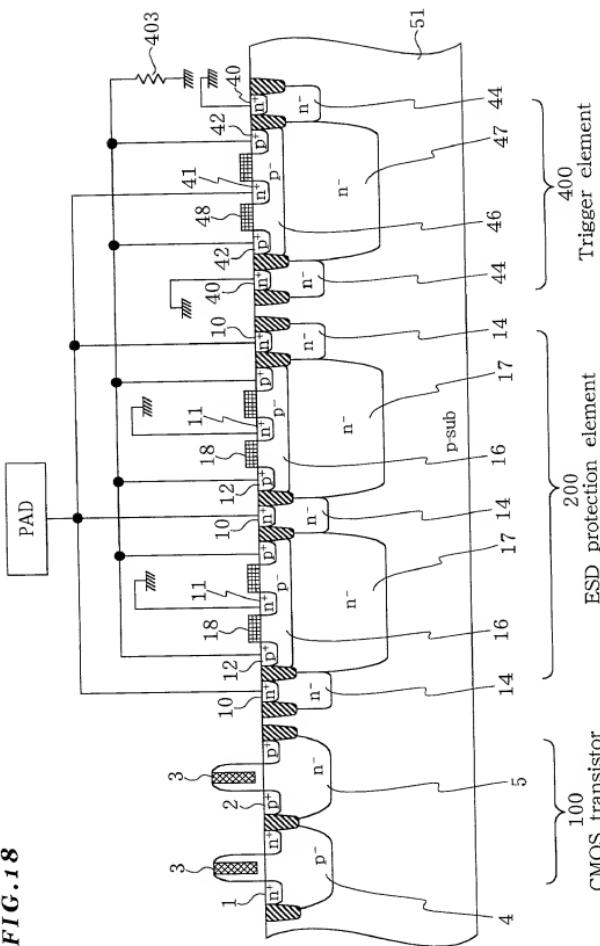


FIG. 19

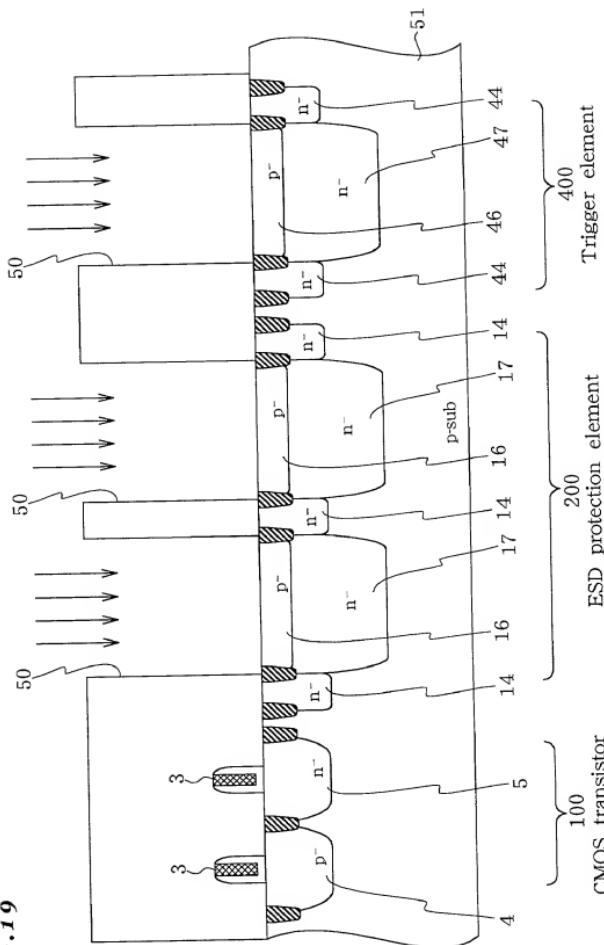


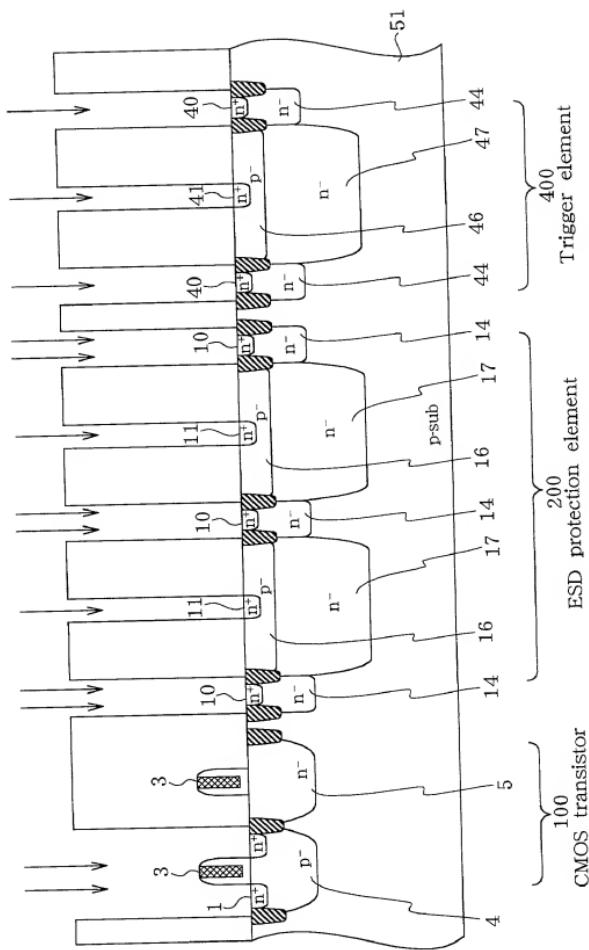
FIG. 20

FIG. 21

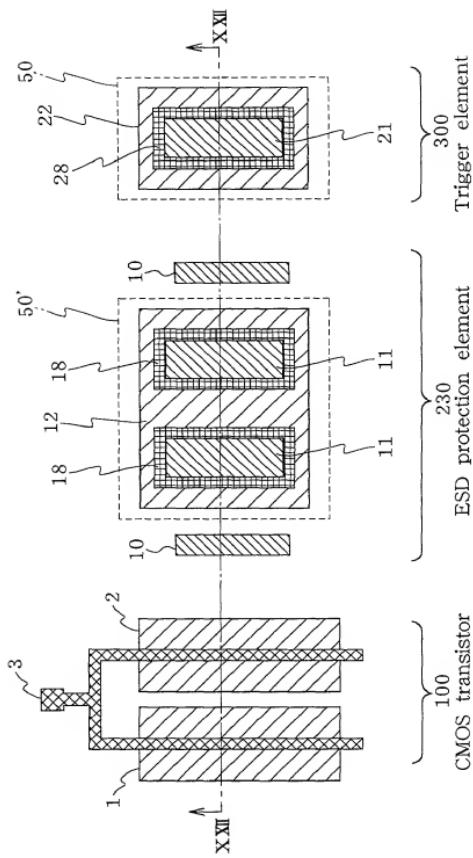


FIG. 22

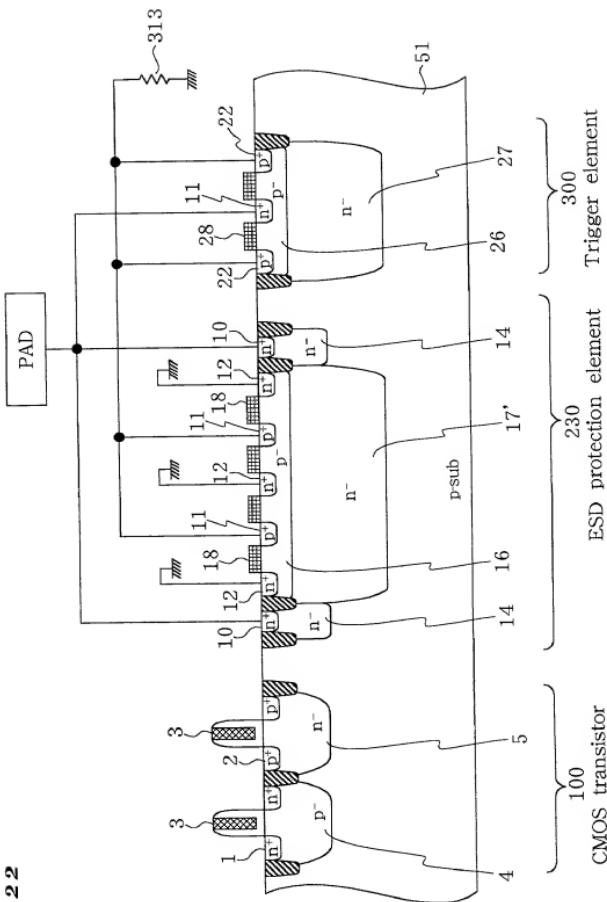


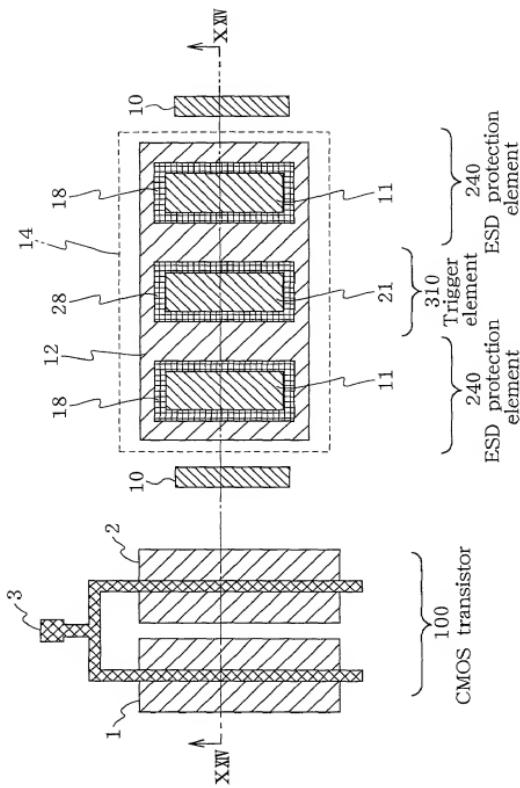
FIG. 23

FIG. 24

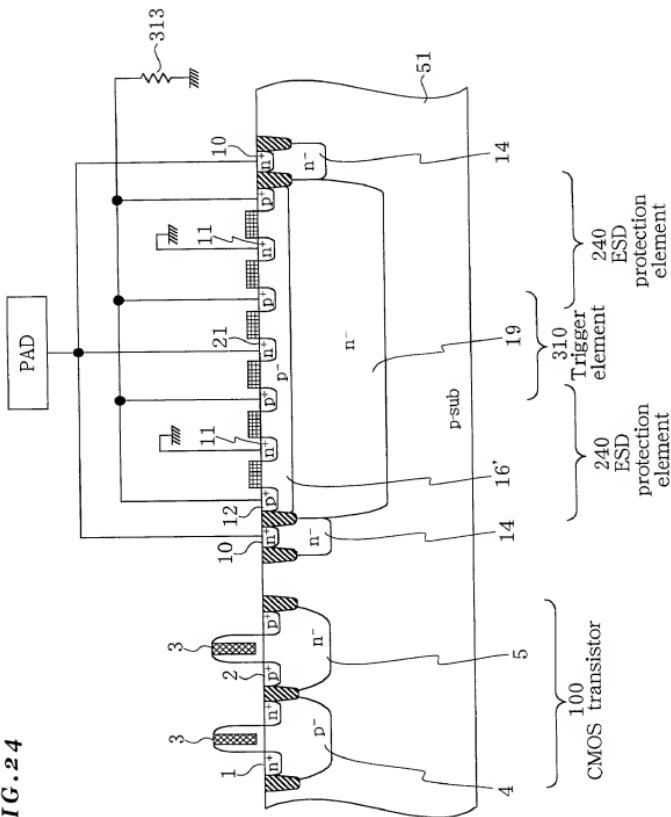


FIG. 25

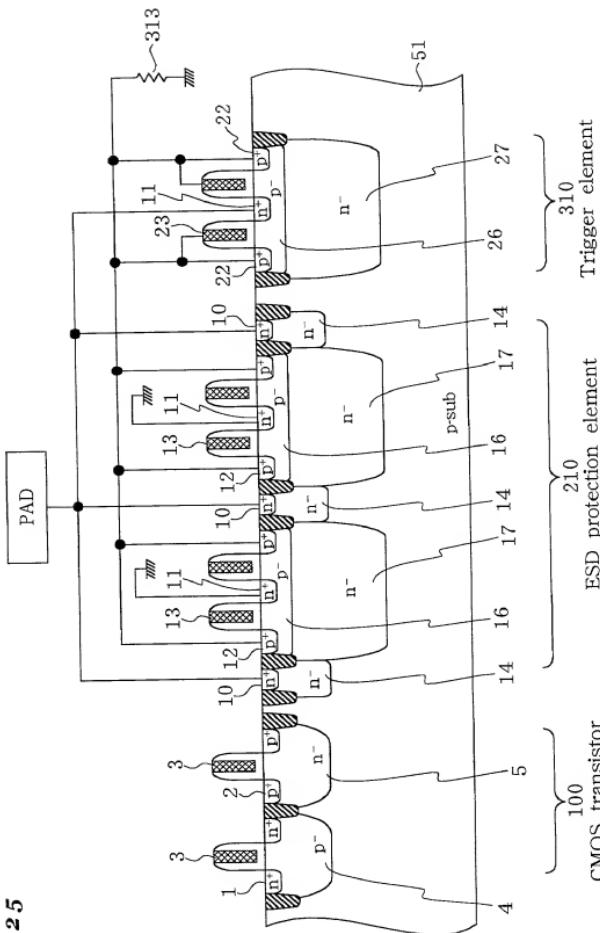


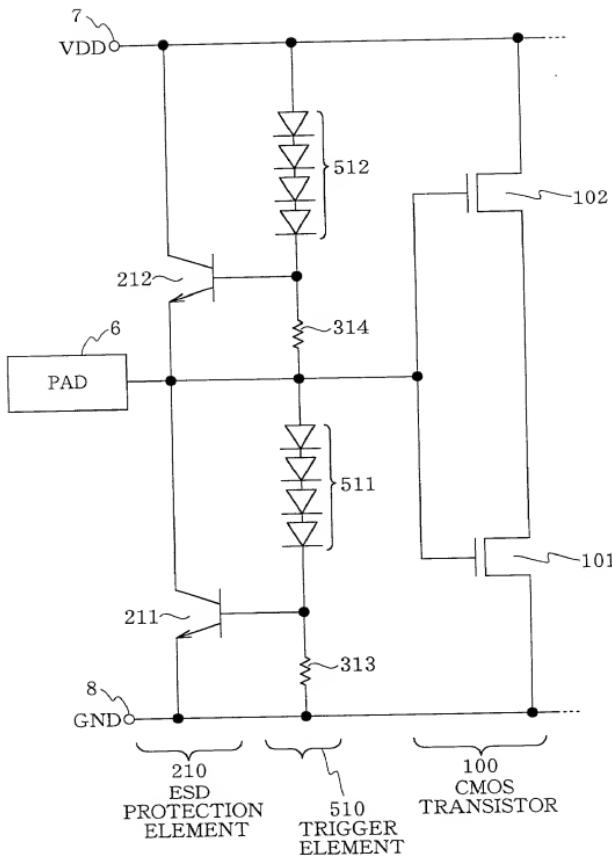
FIG. 26

FIG. 27

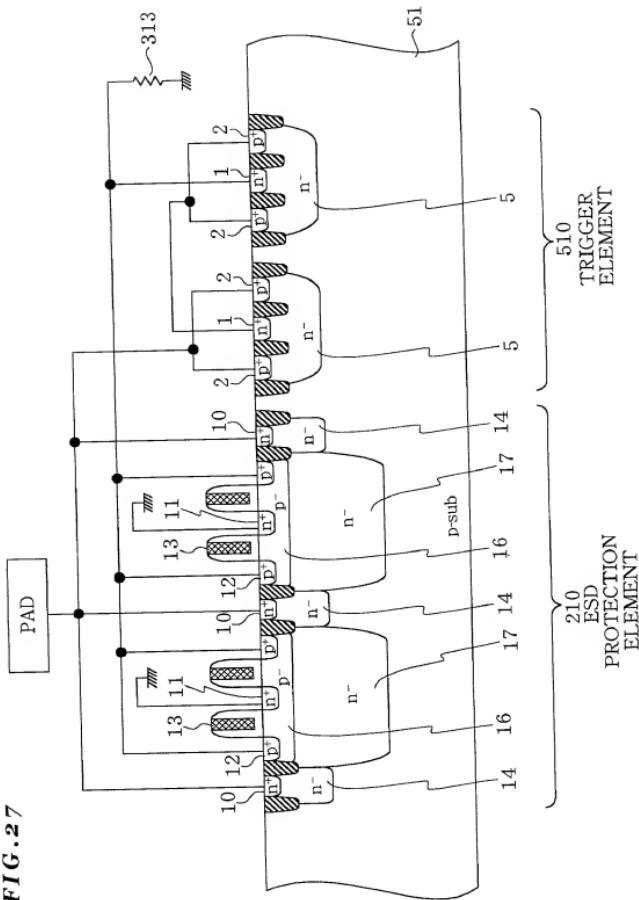
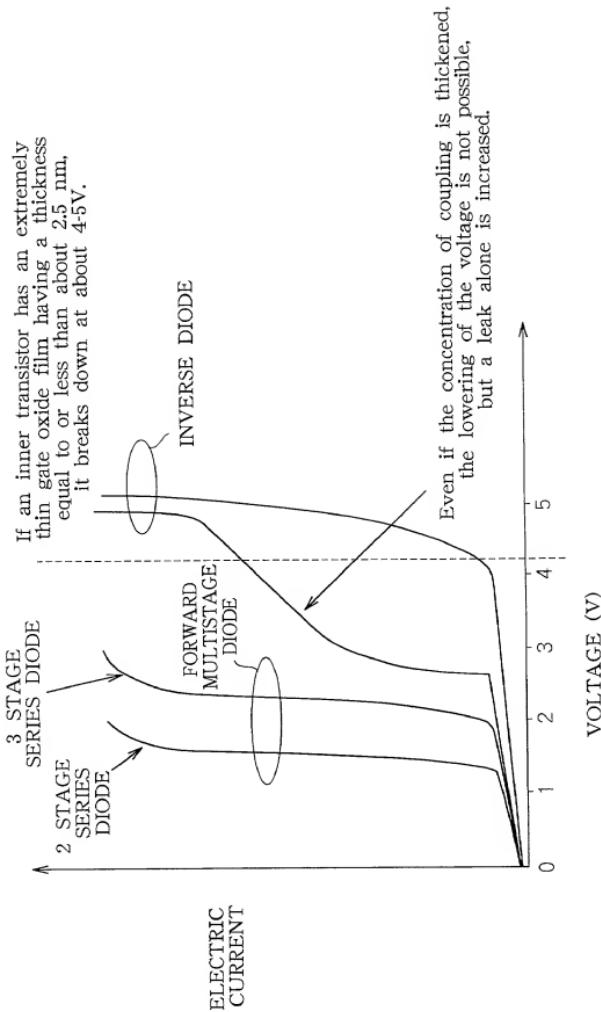
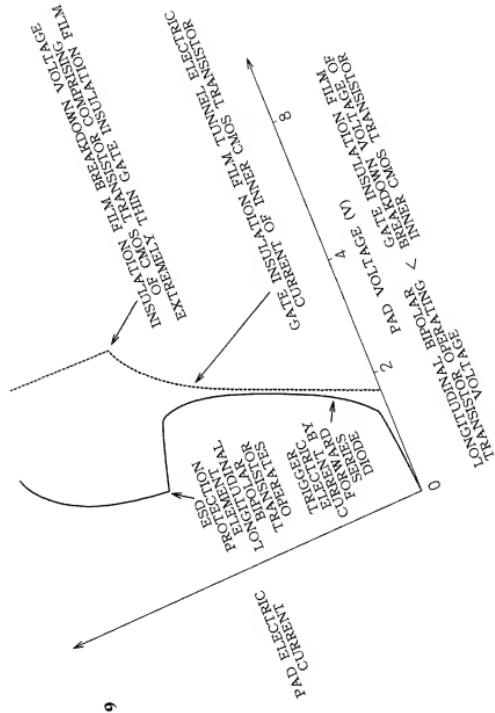


FIG. 2.8

**COMPARISON OF FORWARD SERIES CONNECTION DIODE
AND INVERSE DIODE**





41 G. 29

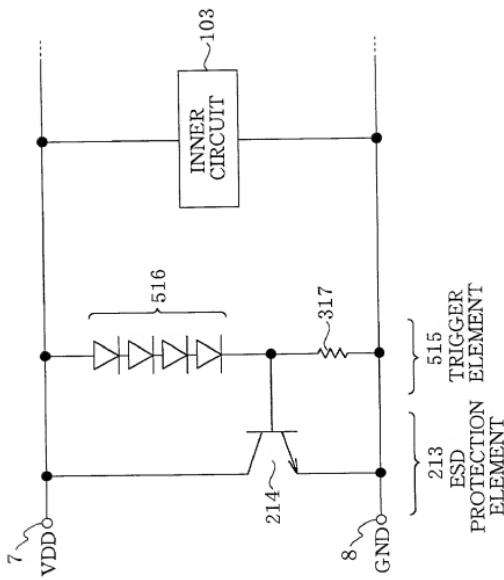


FIG.30

FIG. 31

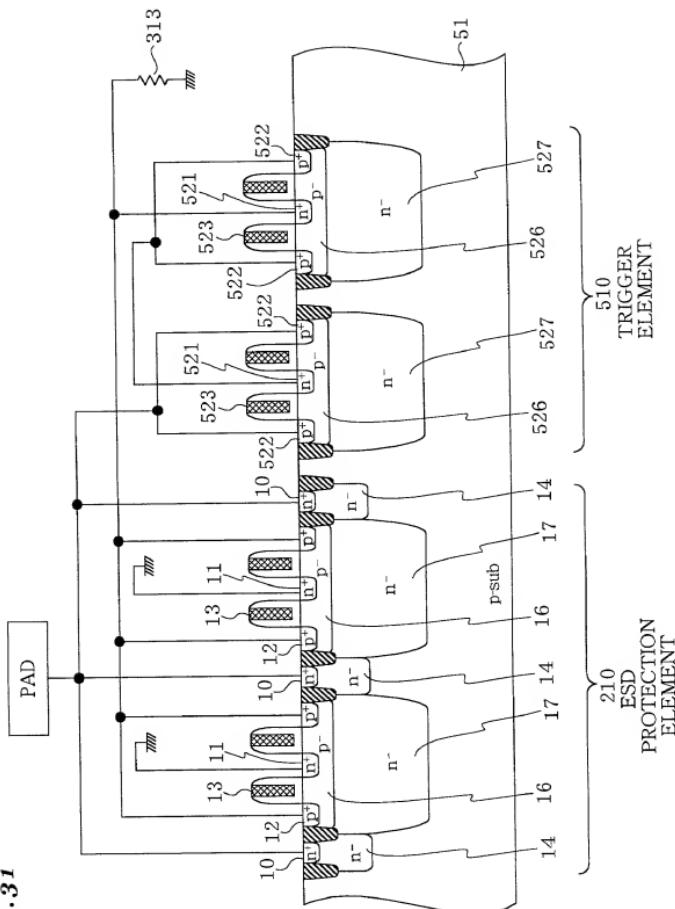
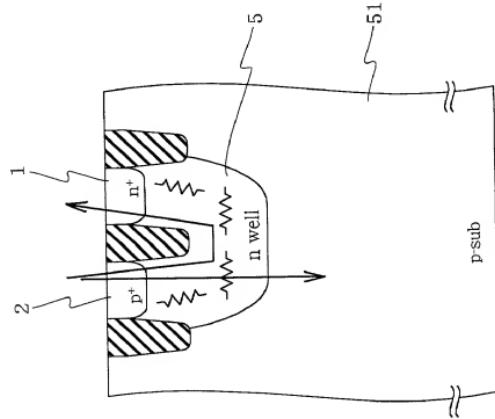


FIG. 32(a)

DIODE COMPRISING
P⁺LAYER/n WELL
FABRICATED BY
EXISTING CMOS PROCESS

**FIG. 32(b)**

DIODE UTILIZING ONE PORTION
OF LONGITUDINAL
BIPOLAR TRANSISTOR

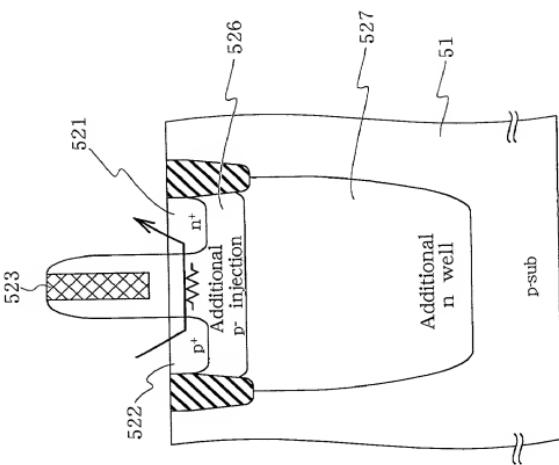
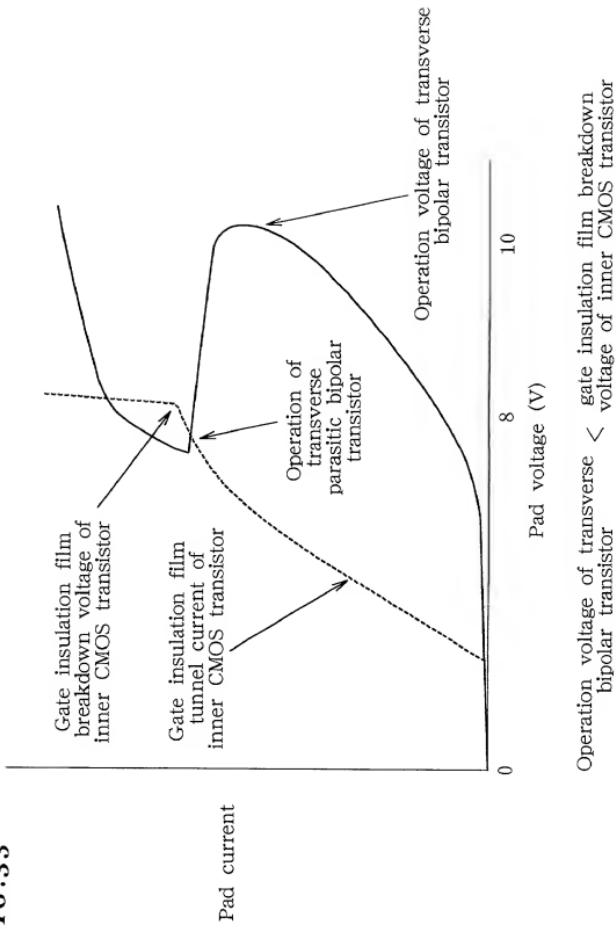


FIG. 3.3

Operation voltage of transverse bipolar transistor < gate insulation film breakdown voltage of inner CMOS transistor